

QUESTTECH

Epoxy & Thermoplastic Sheet Adhesives

Applications

General

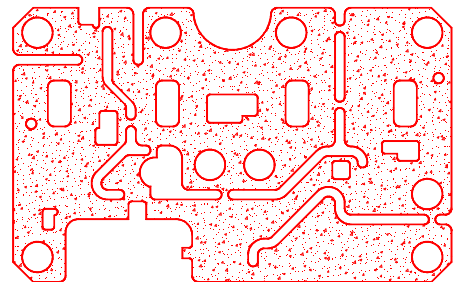
- Any shape required--shape complexity is not a limitation
- No hard tooling charge or non-recurring engineering charge
- No tooling impact for design changes
- No need to stock cut sizes--order only as needed--reduces potential obsolescence
- Reduce risk of material loss due to exceeding shelf life limit
- Fast delivery of any custom shape or size
- Economical small lot quantities or volume runs

Types

- Die Mounting Preforms
- Substrate Mounting Preforms
- Heat spreader mounting
- Package Seal Rings
- R.F. Gaskets and Mounts

Uses

- Microcircuits including:
 - Hybrids Multi-Chip Modules
 - Microwave Monolithics
 - Power Optoelectronics
 - Medical
 - Conventional



Typical .003" Thermoplastic Application

Materials

- Filled and Unfilled
- Electrically Conductive and Non-conductive
- Silver and Gold Filled
- Supported and Unsupported
- Ablefilm, Staystik and other manufacturers

Design Guidelines

Property	Nominal	Units
Smallest Feature	.004	Inches
Minimum Radius	.003	Inches
Feature Tolerances As Cut	+/- .003	Inches
Maximum Thickness	0.025	Inches
Front to Back Taper	10%	Of Material Thickness
Minimum Kerf Width	.010	Inches

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